

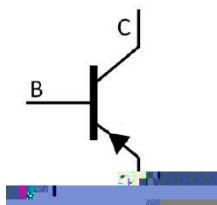
**2SA1201G**  
Rev.E Mar.-2016

SOT-89

PNP

Silicon PNP transistor in a SOT-89 Plastic Package.

High  $f_T$ , high  $V_{CE0}$  , , 2SC2881G



Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-120	V
Collector to Emitter Voltage	$V_{CEO}$	-120	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current-Continuous	$I_C$	-800	mA
Collector Base-Continuous	$I_B$	-160	mA
Collector Power Dissipation	$P_C$	500	mW
Collector Power Dissipation*	* $P_C$	1.0	W
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

\*mounted on ceramic substrate(250mm<sup>2</sup>×0.8t)

\* 250mm<sup>2</sup>×0.8t

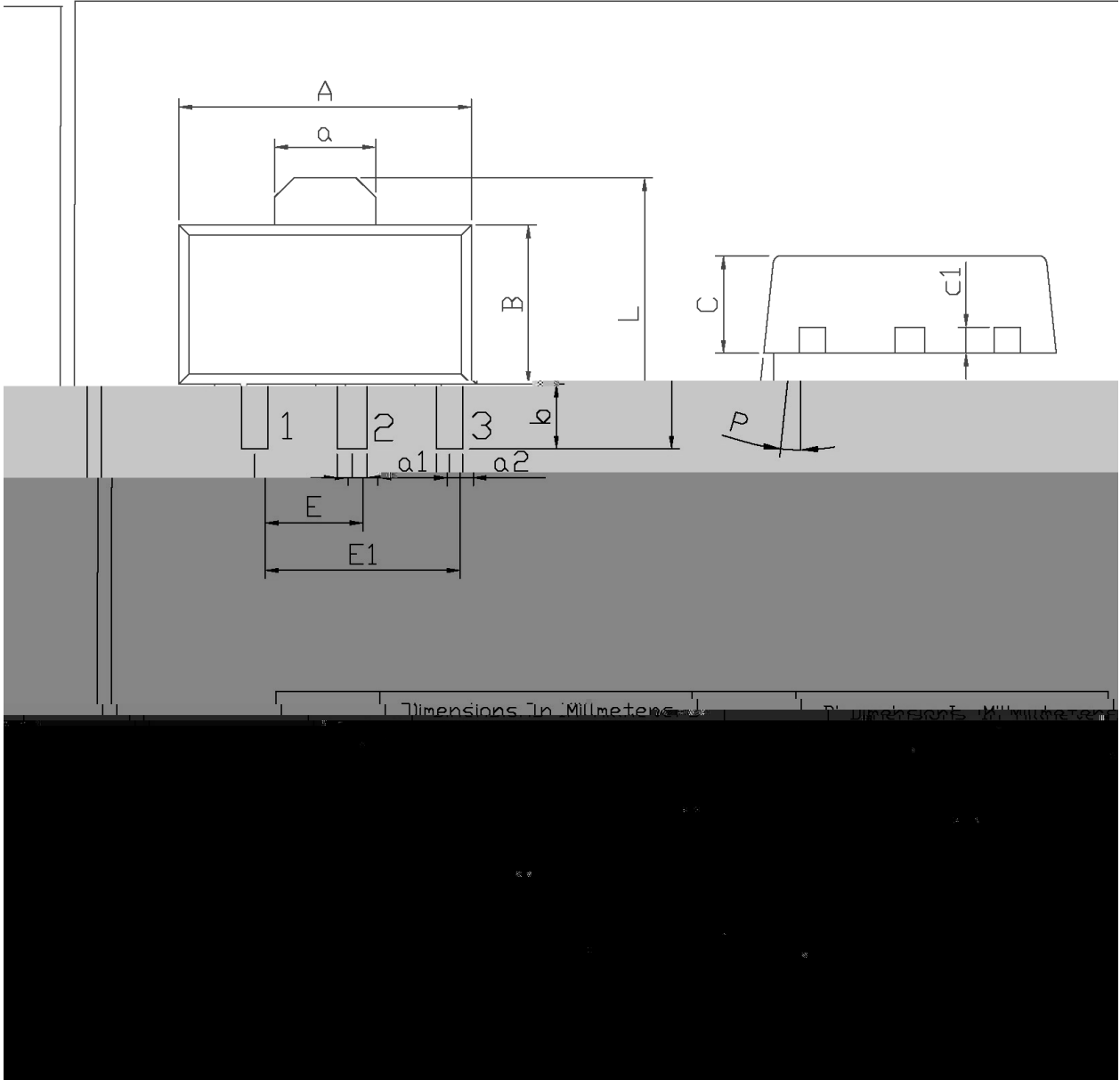
Parameter                      Symbol                      Test Conditions



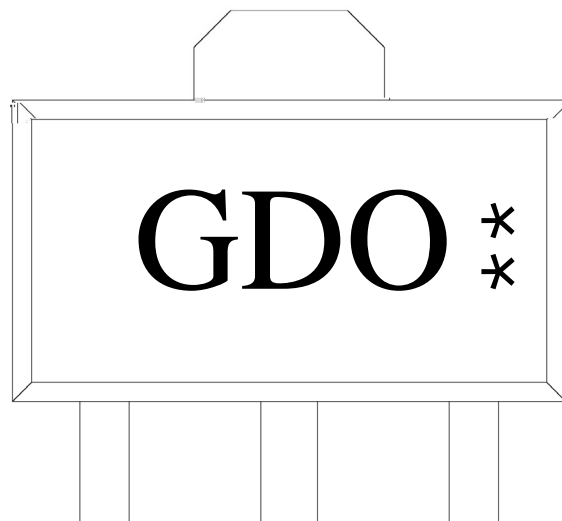
/ Package Dimensions

2SA1201G

单位: mm



/ Marking Instructions



G

D

O

$h_{FE}$

\*\*

Note:

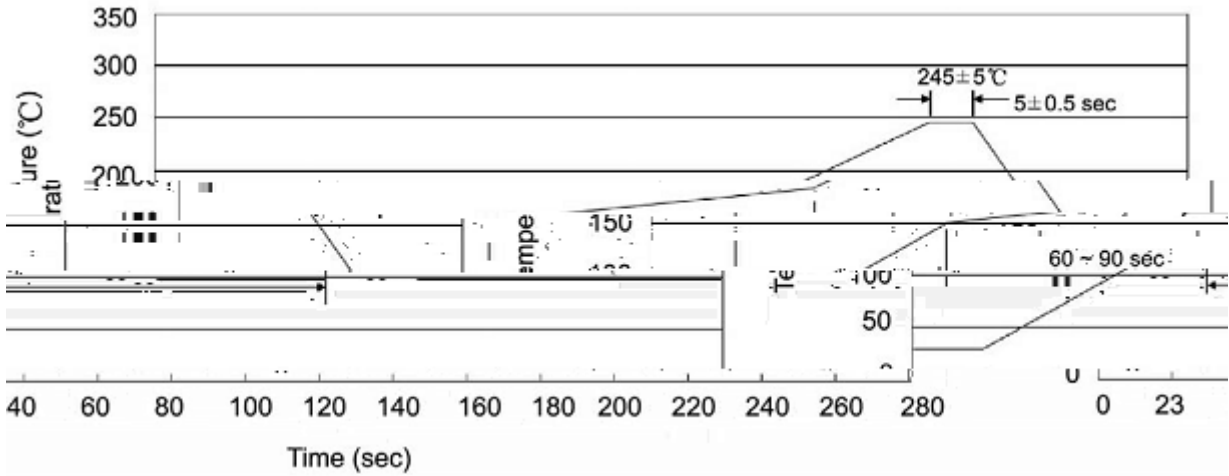
G: Halogen Free Product.

D: Product Type.

O:  $h_{FE}$  Classifications Symbol

\*\* : Lot No. Code, code change with Lot No.

( ) / Resistance to Soldering Heat Test Conditions



Note:

- |   |       |     |    |           |   |
|---|-------|-----|----|-----------|---|
| 1 | 25    | 150 | 60 | 90sec;    | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     |    | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2  | 10 /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-89	1,000	7	7,000	8	56,000	7 ×12	180×120×180	385×257×392

/ Notices